

NPN 100mA 50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value
V <sub>CEO</sub>	50V
Ι <sub>C</sub>	100mA
R <sub>1</sub>	10kΩ

#### Features

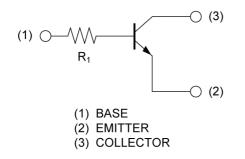
- 1) Built-In Biasing Resistor
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary PNP Types: DTA114T series

## Application

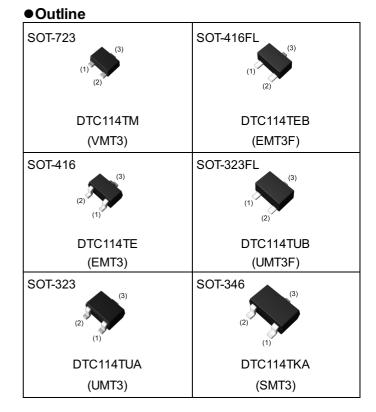
INVERTER, INTERFACE, DRIVER

#### Inner circuit

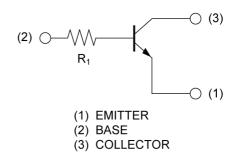
DTC114TM/ DTC114TEB/ DTC114TUB



## Packaging specifications



## DTC114TE/ DTC114TUA/ DTC114TKA



Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTC114TM	SOT-723	1212	T2L	180	8	8000	04
DTC114TEB	SOT-416FL	1616	TL	180	8	3000	04
DTC114TE	SOT-416	1616	TL	180	8	3000	04
DTC114TUB	SOT-323FL	2021	TL	180	8	3000	04
DTC114TUA	SOT-323	2021	T106	180	8	3000	04
DTC114TKA	SOT-346	2928	T146	180	8	3000	04

## **DTC114T** series

## • Absolute maximum ratings ( $T_a = 25^{\circ}C$ )

P	Parameter	Symbol	Values	Unit
Collector-base voltage		V <sub>CBO</sub>	50	V
Collector-emitter voltage		V <sub>CEO</sub>	50	V
Emitter-base voltage			5	V
Collector current		Ι <sub>C</sub>	100	mA
	DTC114TM		150	
	DTC114TEB		150	
Devuer dis siz stiers	DTC114TE		150	
Power dissipation	DTC114TUB		200	— mW
	DTC114TUA		200	
DTC114TKA Junction temperature			200	
		Tj	150	°C
Range of storage tempera	ature	T <sub>stg</sub>	-55 to +150	°C

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Demonster	O: make a l	Q and lititian a		L luait		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	Ι <sub>C</sub> = 50μΑ	50	-	-	V
Collector-emitter breakdown voltage	$BV_{CEO}$	I <sub>C</sub> = 1mA	50	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	Ι <sub>Ε</sub> = 50μΑ	5	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 50V	-	-	500	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 4V	-	-	500	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA	-	-	300	mV
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 1mA	100	250	600	-
Input resistance	R <sub>1</sub>	-	7	10	13	kΩ
Transition frequency	f <sub>T</sub> *2	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz

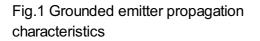
\*1 Each terminal mounted on a reference land.

\*2 Characteristics of built-in transistor

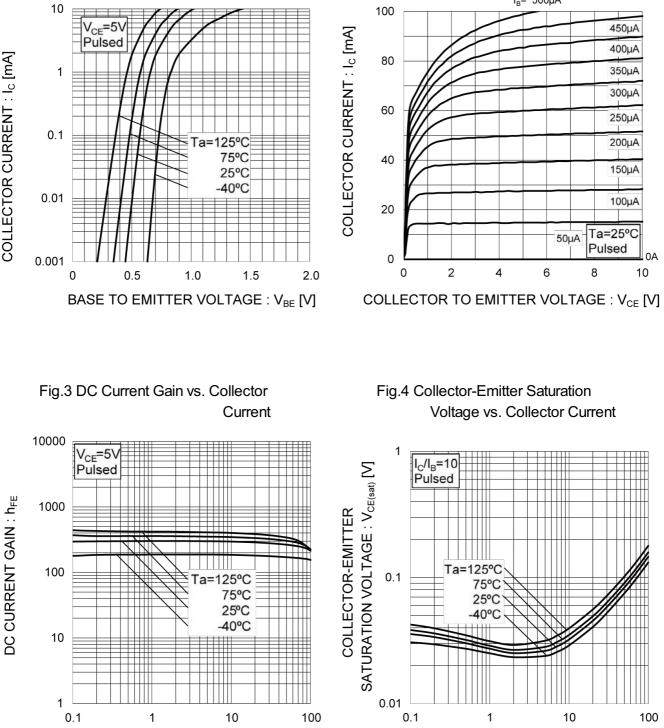
Fig.2 Typical Output Characteristics

I<sub>B</sub>= 500μA

## ● Electrical characteristic curves(Ta=25°C)



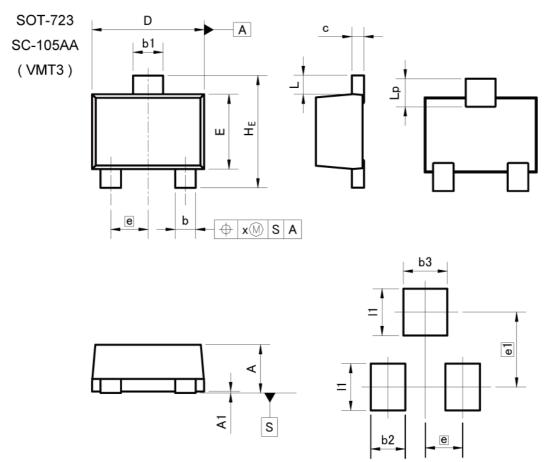
COLLECTOR CURRENT : I<sub>c</sub> [mA]



COLLECTOR CURRENT : Ic [mA]

COLLECTOR CURRENT : Ic [mA]

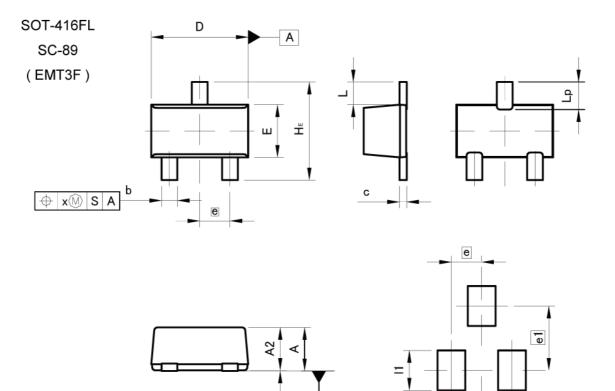




Pattern of terminal position areas [Not a pattern of soldering pads]

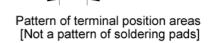
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
с	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.40		0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х		0.10		0.004
	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<u></u> 2	0.37		0.015
b3	<u>144</u> 5	0.47	-	0.019
e1	0.	80	0.0	31
11		0.50	1	0.020





Ł

Ś



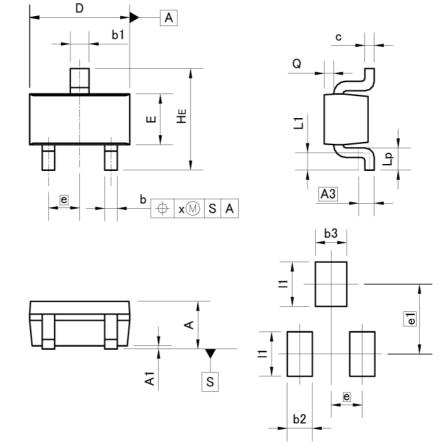
b2

	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
A2	0.60	0.80	0.024	0.031
b	0.21	0.36	0.008	0.014
с	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.50		0.020	
HE	1.50	1.70	0.059	0.067
L	0.	37	0.015	
Lp	0.35	0.55	0.014	0.022
x		0.10	-	0.004
	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<del></del> .	0.46	-	0.018
e1		1.05	-	0.041
11	-	0.65	-	0.026





(EMT3)

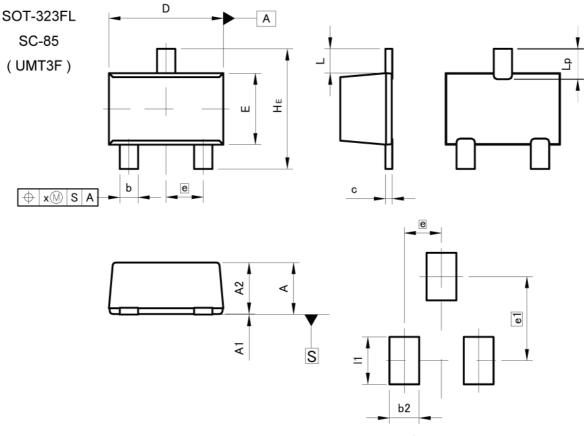


Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIM	ETERS	INCHES	
	MIN	MAX	MIN	MAX
A	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
с	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10	÷	0.004	0 <del></del>
Lp	0.15		0.006	233
Q	0.05	0.25	0.002	0.010
x	27	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2		0.40	-	0.016
b3	<del></del>	0.50	. <del></del> (	0.020
e1	1.10		0.0	043
11	<del></del>	0.70	-	0.028



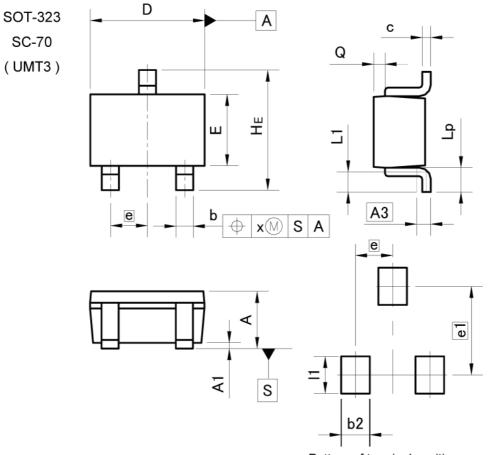


Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INCHES	
	MIN	MAX	MIN	MAX
A	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
с	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.	65	0.026	
HE	2.00	2.20	0.079	0.087
L	0.4	25	0.017	
Lp	0.43	0.63	0.017	0.025
x	<del></del> .:	0.10	-	0.004
		5		
	MILIM	ETERS	INCHES	
DIM -	MIN	MAY	MIN	MAY

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2		0.52		0.020
e1	1.4	7	0.0	058
11	<u>200</u> 4	0.83	5776	0.033

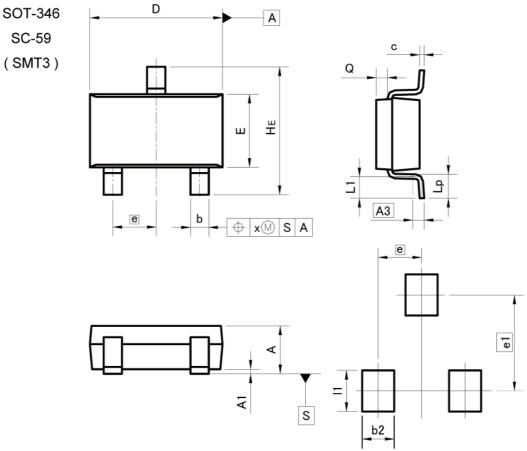




Pattern of terminal position areas [Not a pattern of soldering pads]

	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.3	25	0.0	10
b	0.25	0.40	0.010	0.016
с	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.10	0.40	0.004	0.016
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	=	0.10	-	0.004
	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
b2	<u>1999</u>	0.50		0.020
e1	1.	55	0.0	61
11		0.65		0.026





Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INCHES	
	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x		0.10	4 <del>7</del>	0.004
у	=1	0.10	2 <del></del>	0.004
	MILIMETERS		INCHES	
DIM -	12/2017			100000

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	2	0.024
e1	2.10		0.083	
11	-10	0.90	( <b>7</b>	0.035



# Notice

#### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

	JAPAN	USA	EU	CHINA
I	CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
	CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

#### **Precaution Regarding Intellectual Property Rights**

- All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
- 2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
- 3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

#### **Other Precaution**

- 1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- 3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.